

| Electronic Patent Application Fee Transmittal | | | | |
|--|--|----------|--------|----------------------|
| Application Number: | 10055560 | | | |
| Filing Date: | 22-Jan-2002 | | | |
| Title of Invention: | Integrated chip package structure using metal substrate and method of manufacturing the same | | | |
| First Named Inventor/Applicant Name: | Mou-Shiung Lin | | | |
| Filer: | Winston Hsu | | | |
| Attorney Docket Number: | MEGP0009USA | | | |
| Filed as Large Entity | | | | |
| Utility under 35 USC 111(a) Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|---|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Submission- Information Disclosure Stmt | 1806 | 1 | 180 | 180 |
| Total in USD (\$) | | | | 180 |